

**STRUCTURE AND METHOD OF
EMBEDDING COMPONENTS IN MULTI-LAYER SUBSTRATES**

ABSTRACT OF THE DISCLOSURE

A method for producing a circuit board having an integrated electronic component comprising providing a circuit board substrate having a first substrate surface and a second substrate surface, securing an integrated electronic component to the first substrate surface, and disposing a first dielectric layer on the first substrate surface and over the first integrated electronic component. The method additionally includes disposing a metallic layer on the first dielectric layer to produce an integrated electronic component assembly, producing in the integrated electronic component assembly at least one via having a metal lining in contact with the metallic layer, and disposing a second dielectric layer over the via and over the metallic layer. At least one metal-lined opening is formed in the second dielectric layer and in the first dielectric layer to expose at least part of the integrated electronic component, and to couple the metal lining of the opening to the first integrated electronic component to produce a circuit board having at least one integrated electronic component. A multi-layer printed circuit board having at least one prefabricated, integrated electronic component.

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